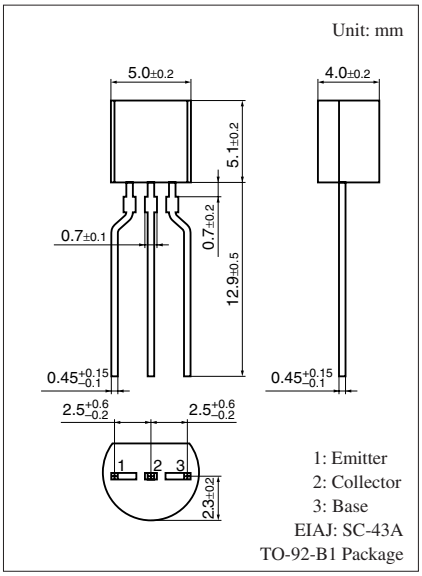
2SC2925

Silicon NPN epitaxial planar type

For low-frequency output amplification



■ Features

- High forward current transfer ratio h_{FE}
- Low collector-emitter saturation voltage $V_{CE(sat)}$

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	60	V
Collector-emitter voltage (Base open)	V_{CEO}	50	V
Emitter-base voltage (Collector open)	V_{EBO}	15	V
Collector current	I_C	0.7	A
Peak collector current	I_{CP}	1.5	A
Collector power dissipation	P_C	750	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

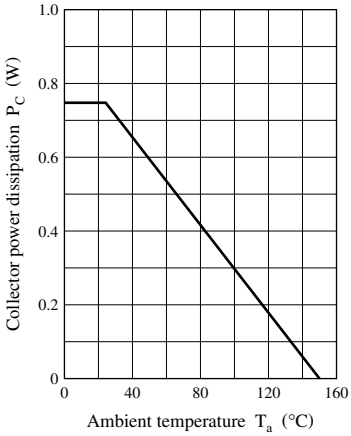
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	I_C = 10 µA, I_E = 0	60			V
Collector-emitter voltage (Base open)	V_{CEO}	I_C = 1 mA, I_B = 0	50			V
Emitter-base voltage (Collector open)	V_{EBO}	I_E = 10 µA, I_C = 0	15			V
Collector-base cutoff current (Emitter open)	I_{CBO}	V_{CB} = 20 V, I_E = 0			1	µA
Collector-emitter cutoff current (Base open)	I_{CEO}	V_{CE} = 20 V, I_B = 0			10	µA
Forward current transfer ratio *	h_{FE}	V_{CE} = 10 V, I_C = 150 mA	400	1 000	2 000	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	I_C = 500 mA, I_B = 50 mA		0.15	0.40	V
Collector output capacitance (Common base, input open circuited)	C_{ob}	V_{CB} = 10 V, I_E = 0, f = 1 MHz		11	15	pF

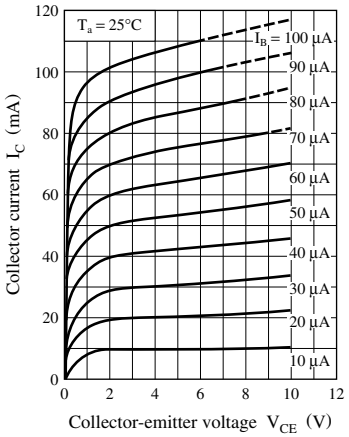
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Rank classification

Rank	R	S	T
h_{FE}	400 to 800	600 to 1 200	1 000 to 2 000

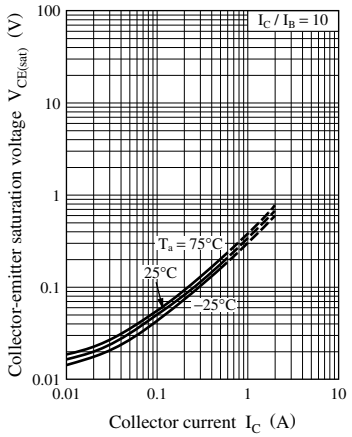
P_C — T_a



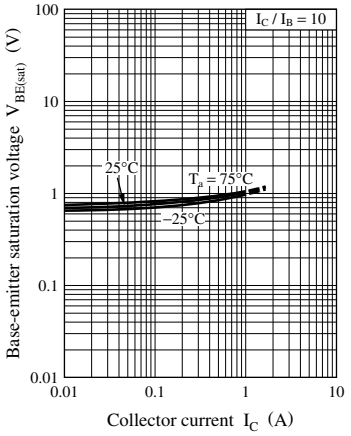
I_C — V_{CE}



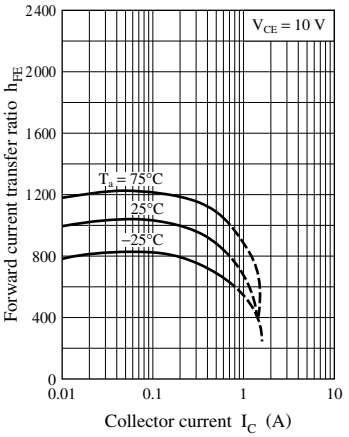
$V_{CE(sat)}$ — I_C



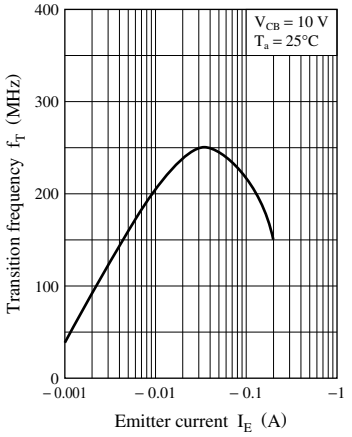
$V_{BE(sat)}$ — I_C



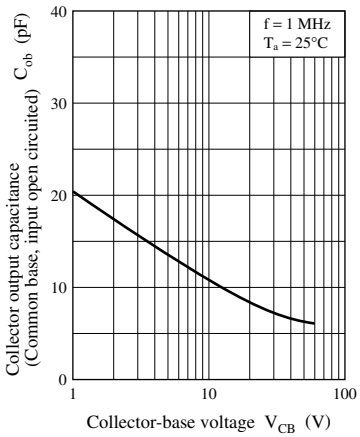
h_{FE} — I_C



f_T — I_E



C_{ob} — V_{CB}



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